

Amendments to the Specification

Please replace the paragraph bridging pages 15 and 16 with the following rewritten paragraph:

--The function of the film 7 as a non-wettable dam is illustrated in FIG. 3. The non-wettable dam 7a, in combination with the UBM pad 5 (and the optional sealant feature 7b, if used) completely seals the interconnect metal 3 of the circuit from exposure to the solder 8. The solder, after wet-back, should be in contact only with the thin gold cap 13, which it consumes, the nickel barrier 5b and the dam 7a. Consequently, metal ~~FILM~~ film 7 fully covers the sidewalls of the pad 5 and protects the interconnect 3. A thickness of several hundred angstroms should be sufficient to ensure this coverage if the substrate is held in a rotating planetary fixture as the titanium film is deposited.--